



Assembly:	ASEM
Size (mm):	4 x 4
Lead pitch (mm):	0.4
MSL:	3
Reflow max (°C):	260

Materials	% of Total Pkg. Wt.	Weight (g)	% of Total Pkg. Wt.	Weight (g)	Material Analysis(Substance)	CAS #	Material % of Subst.	Notes / Assumptions:
IC Chip (Die)	4.95%	0.00130	4.9539%	0.00130	Silicon	7440-21-3	100.000%	Die size: 1.50 x 1.50 mm
Mold Compound	62.8535%	0.01646						KE-G1250LKDS-C Kyocera
			55.4782%	0.01453	Fused Silica	60676-86-0 7631-86-9	88.266%	
			3.5898%	0.00094	Epoxy resin	Trade secret	5.711%	
			3.5898%	0.00094	Phenol Resin	Trade secret	5.711%	
			0.1958%	0.00005	Carbon Black	1333-86-4	0.312%	
							100.00%	
D/A Tape	0.2349%	0.00006						FH-900T-25_HR9004T Resonac
			0.0334%	0.00001	Epoxy Resin	Trade secret	14.218%	
			0.0334%	0.00001	Phenol Resin	Trade secret	14.218%	
			0.0122%	0.00000	SiO2 Filler	Trade secret	5.213%	
			0.1559%	0.00004	(Meta)Acrylic Copolymer	Trade secret	66.351%	
							100.00%	
Wire	1.0481%	0.00027						0.7 MIL Pd coated Cu Nippon
			1.0318%	0.00027	Copper	7440-50-8	98.450%	
			0.0162%	0.00000	Palladium	7440-05-3	1.550%	
							100.00%	
Solder Balls	2.6607%	0.00070						SAC105 wait for confirmation Senju
			2.6208%	0.00069	Tin (Sn)	7440-31-5	98.500%	
			0.0266%	0.00001	Silver (Ag)	7440-22-4	1.000%	
			0.0133%	0.00000	Copper (Cu)	7440-50-8	0.500%	
						100.00%		
Substrate	28.2489% 4.2373%	0.00740						BT Resin CCL-HL832NX-A
			2.5110%	0.00066	Copper thickness	7440-50-8	8.8889%	
			0.5493%	0.00014	Nickel Plating	7440-02-0	1.9444%	
			0.2354%	0.00006	Gold Plating	7440-57-5	0.8333%	
			0.9416%	0.00025	Copper thickness in hole	7440-50-8	3.3333%	
				0.00111			15.0000%	
Foil	19.6173%							BT RESIN CCL-HL832NX (A-)JHS
			5.1005%	0.00134	Thermosetting resin (including filler)	NA	18.0556%	
			5.1005%	0.00134	Glass cloth	65997-17-3	18.0556%	
			9.4163%	0.00247	Copper foil	7440-50-8	33.3333%	
			0.00514			69.4444%		
Solder Mask	0.0439%							Solder mask PSR4000 AUS 308
			0.1758%	0.00005	Morpholine derivative	NA	0.6222%	
			2.0206%	0.00053	Barium Sulfate	7727-43-7	7.1530%	
			0.0439%	0.00001	Silica	7631-86-9	0.1556%	
			0.1758%	0.00005	Talc	14807-96-6	0.6222%	
			1.0546%	0.00028	Dipropylene Glycol Monomethyl Ether	34590-94-8	3.7333%	
			0.9228%	0.00024	Epoxy Resin	85954-11-6	3.2667%	
			0.0007%	0.00000	Melamine	108-78-1	0.0026%	
			0.00115			15.5556%		

 Br/Cl/Sb

